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| <u>Title:</u> | Gas Assisted Etching and Material Deposition on micro- and nano- scale |
| <u>Training duration:</u> | <i>3 days</i> |
| <u>Training cost:</u> | <i>Groups of 1 – 3 trainees, US\$3600 per group</i> |
| <u>Background required:</u> | <i>Basic FIB operator training, basic background in physics, chemistry, or material science</i> |
| <u>Student Objective:</u> | <i>Understanding basics of GAE and material deposition, influence of beam raster parameters on etching and deposition processes, Ga implantation, specifics of in-via milling and deposition</i> |
| <u>Equipment:</u> | <i>Micrion 2000, 2500, 9000, 9100, 986, 986FC, Vectra 986(+), VectraVision, any FIB or FEB equipment</i> |
| <u>Syllabus:</u> | <i>TBD, available online by June 30, 2004</i> |